United States Patent [19]

Hollingsworth et al.

[11] **Des. 247,032**

[45] ** **Jan. 24, 1978**

[54] **LOW PROFILE INTEGRATED CIRCUIT DIP SOCKET**

[75] Inventors: **Gene C. Hollingsworth**, Cerritos; **Eugene G. Freehauf**, Ontario, both of Calif.

[73] Assignee: **Zero Corporation**, Burbank, Calif.

[**] Term: **14 Years**

[21] Appl. No.: **587,394**

[22] Filed: **June 16, 1975**

[51] **Int. Cl.** .... **D13—03**
[52] **U.S. Cl.** **D13/24**
[58] **Field of Search** .... D26/1 R, 1 A, 1 D, 1 E; 339/17 CF, 17 LM, 17 M, 18 R, 18 B, 198 R, 198 G, 176 MP

[56] **References Cited**

U.S. PATENT DOCUMENTS

2,832,942	4/1958	French	339/17 LM X
3,732,529	5/1973	Weisenburger	339/17 CF X

OTHER PUBLICATIONS

Electronic Molding Corp. Product Bulletin FS-16, Rec'd May 1971, Sockets.

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[57] **CLAIM**

The ornamental design for a low profile integrated circuit dip socket, substantially as shown.

DESCRIPTION

FIG. **1** is a right front perspective view of a low profile integrated circuit socket showing our new design;
FIG. **2** is a front end elevational view thereof;
FIG. **3** is a rear end elevational view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a right front perspective view of an eight pin socket embodiment thereof;
FIG. **6** is a bottom plan view of the socket of FIG. **5**;
FIG. **7** is a front end elevational view thereof;
FIG. **8** is a rear end elevational view thereof;
FIG. **9** is a rear perspective view of the socket of FIG. **1**; and
FIG. **10** is a rear perspective view of the socket of FIG. **5**.

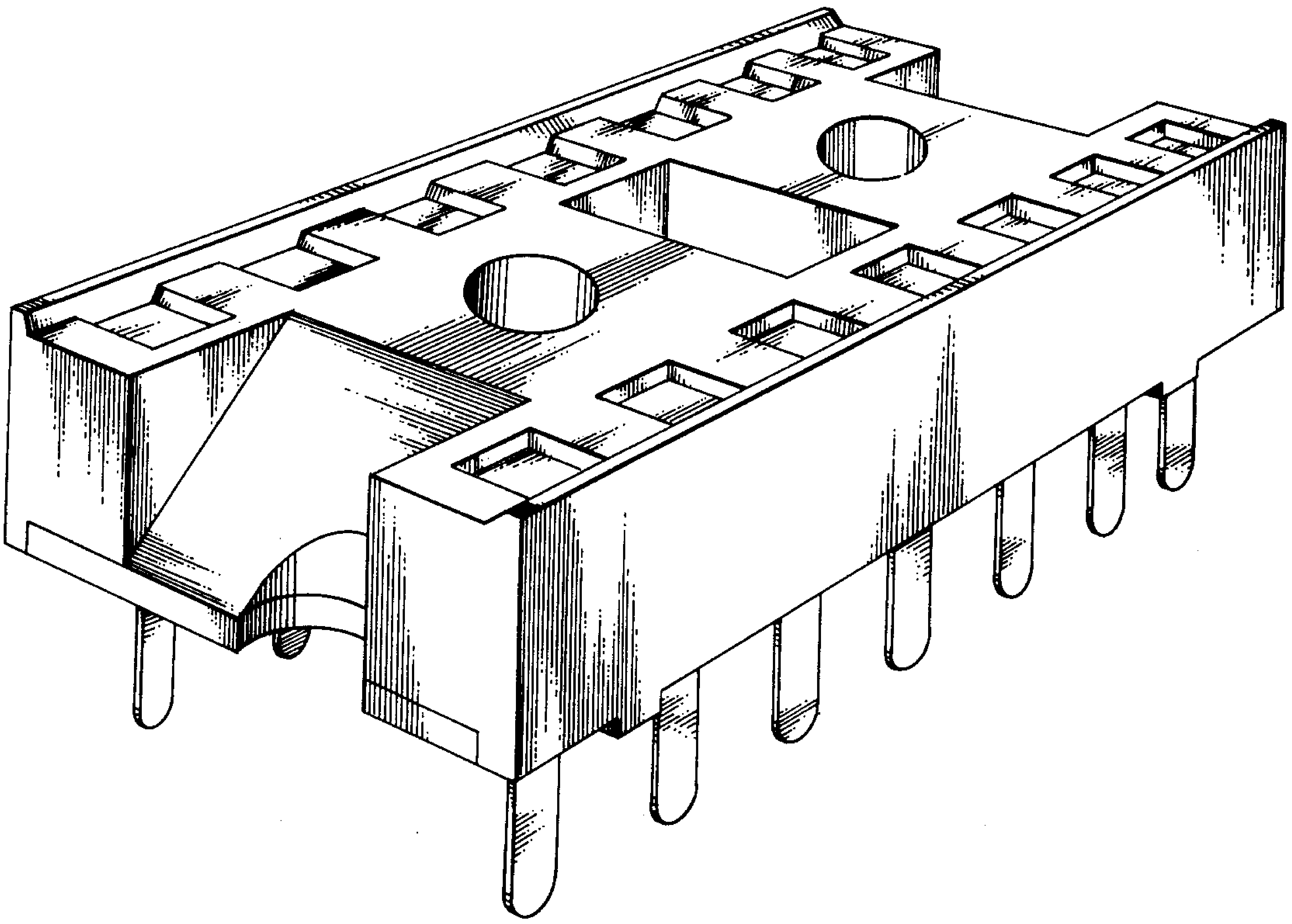
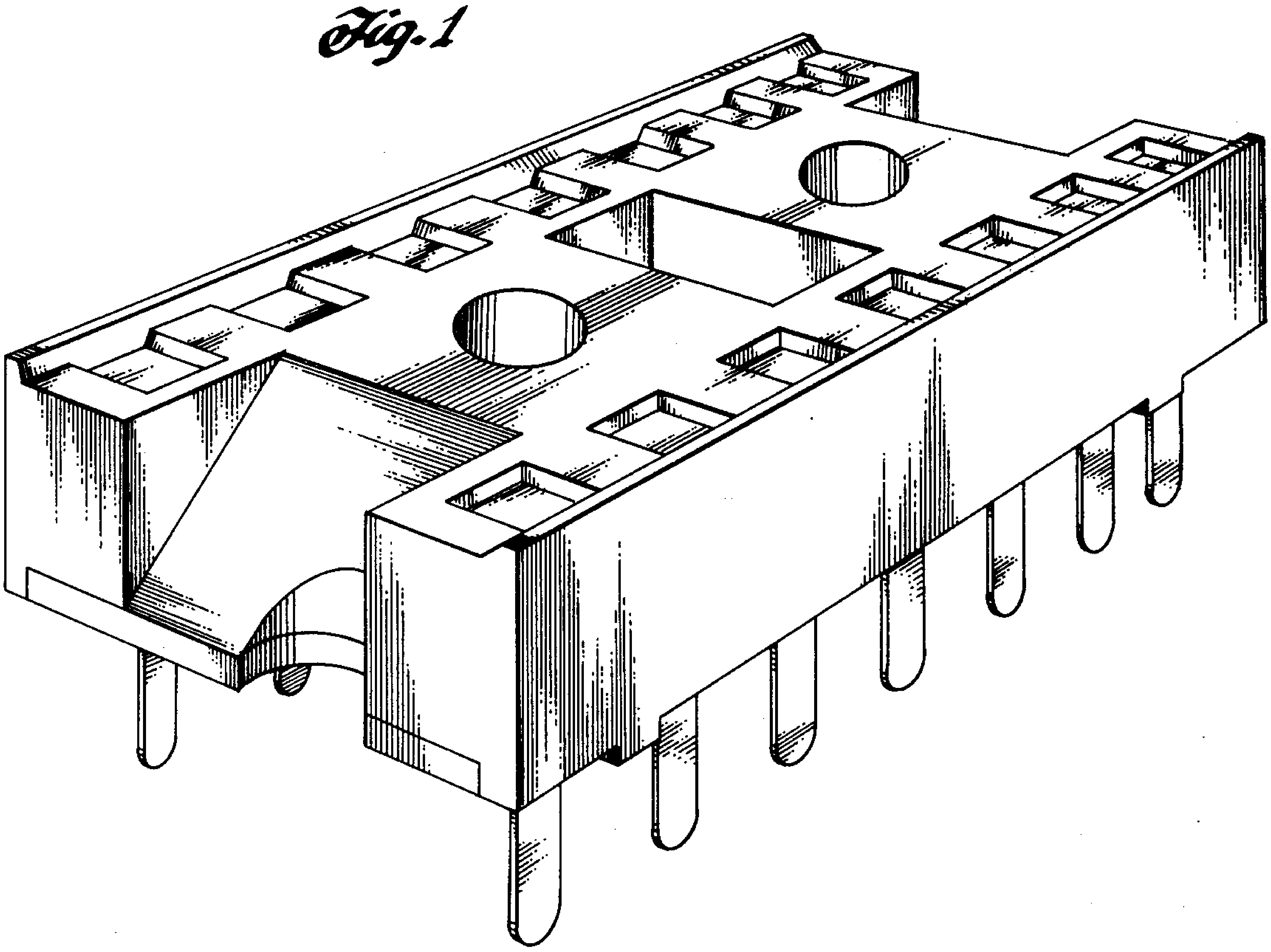


Fig.1



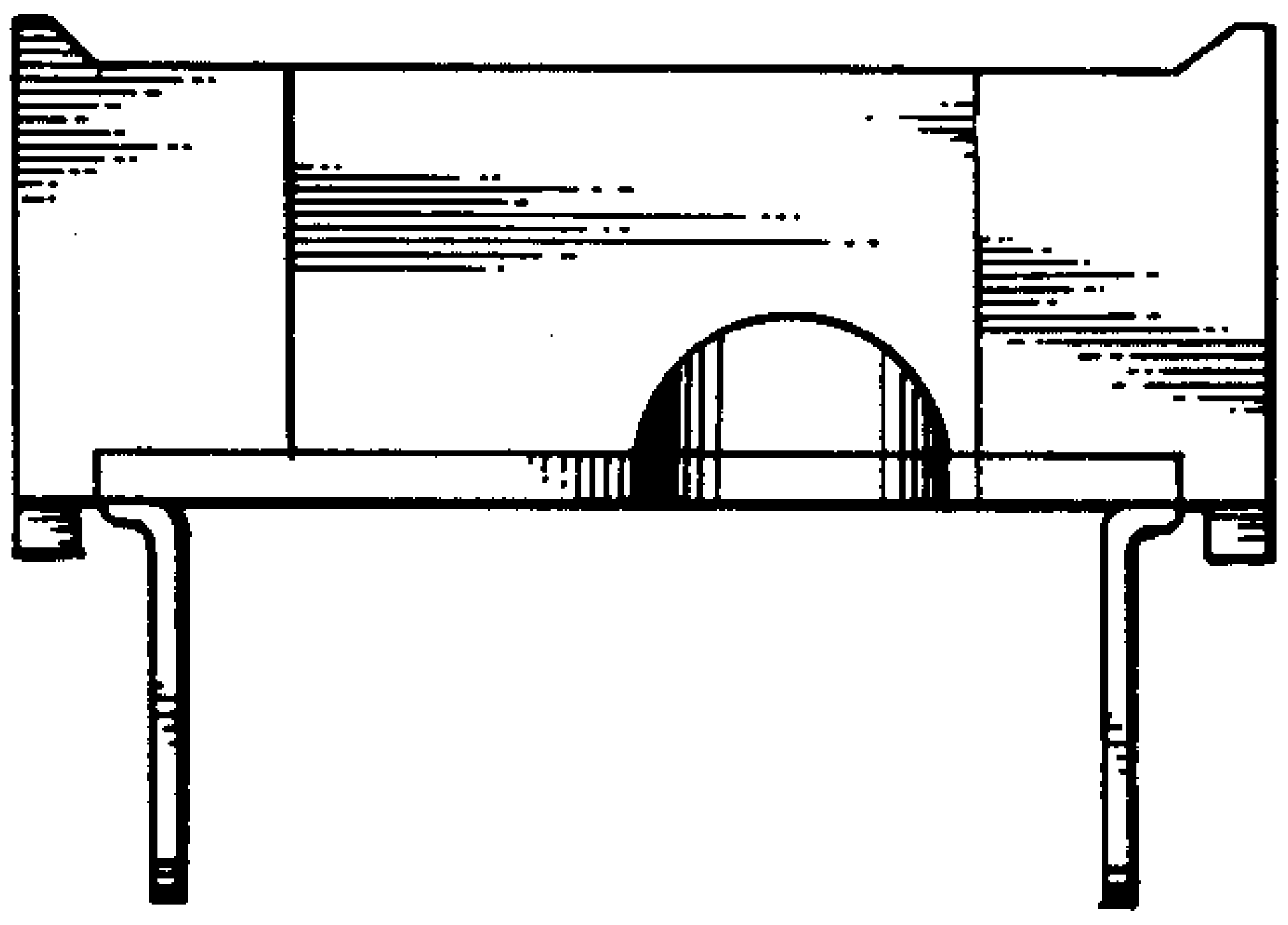


Fig.2

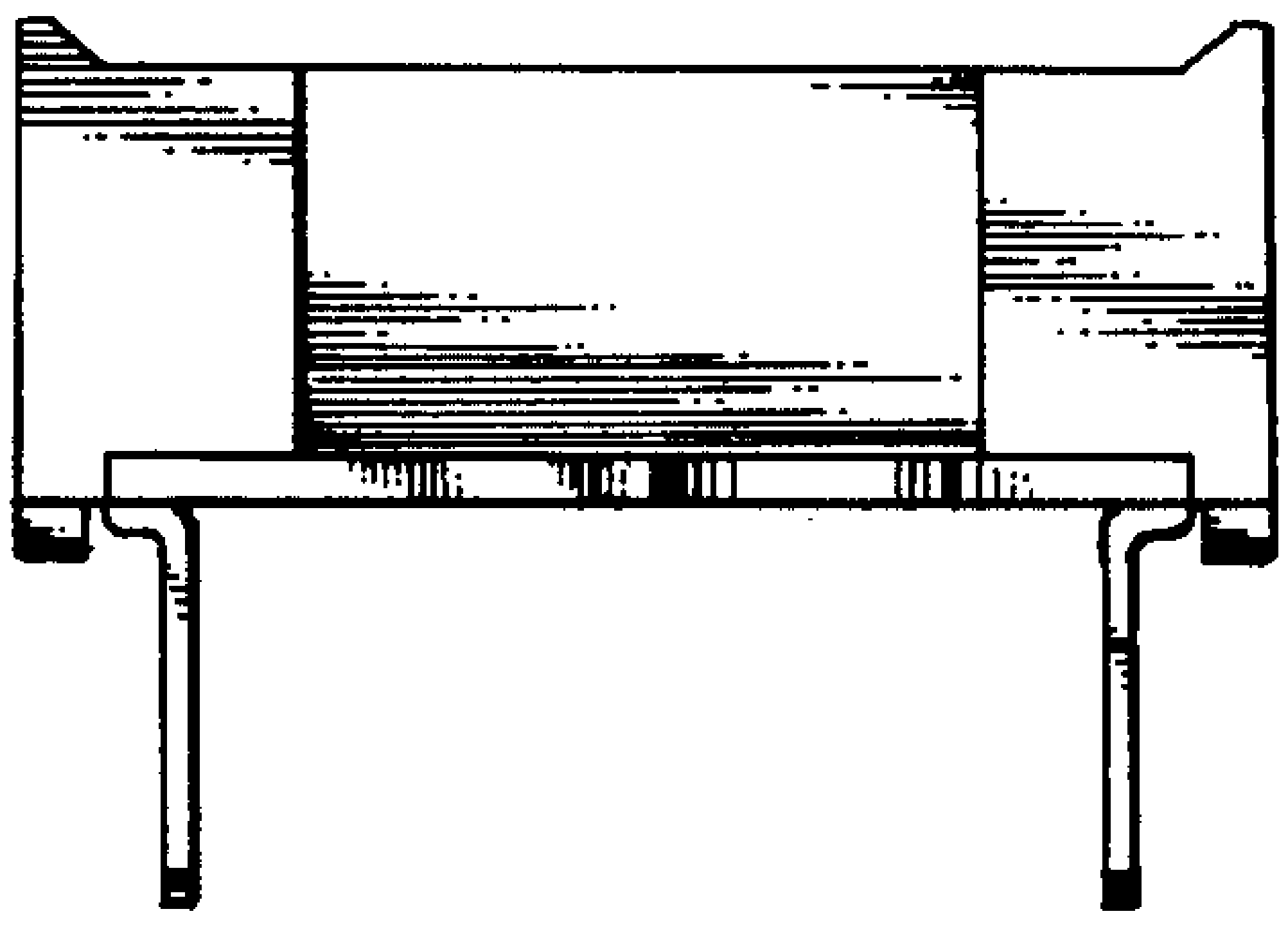


Fig.3

Fig. 4

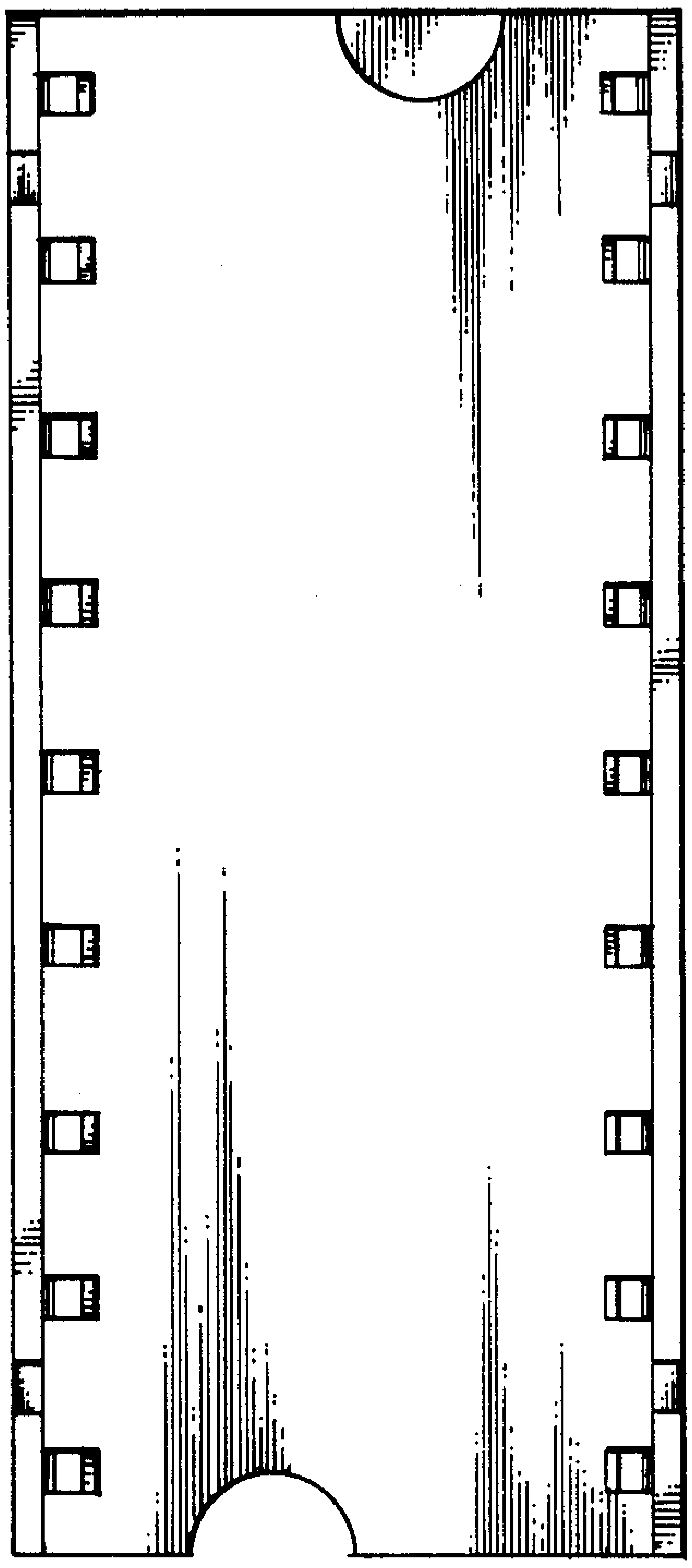


Fig. 5

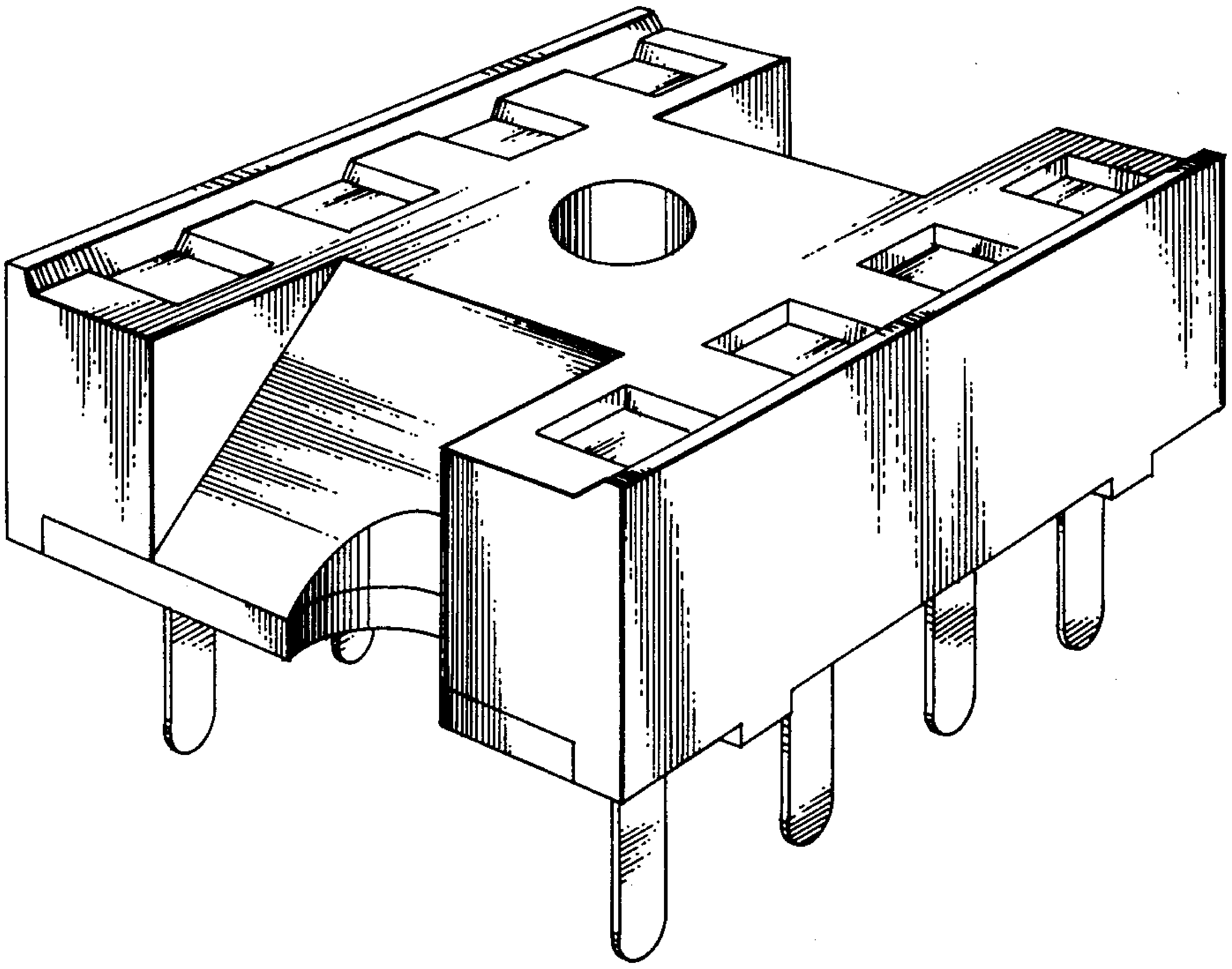


Fig. 6

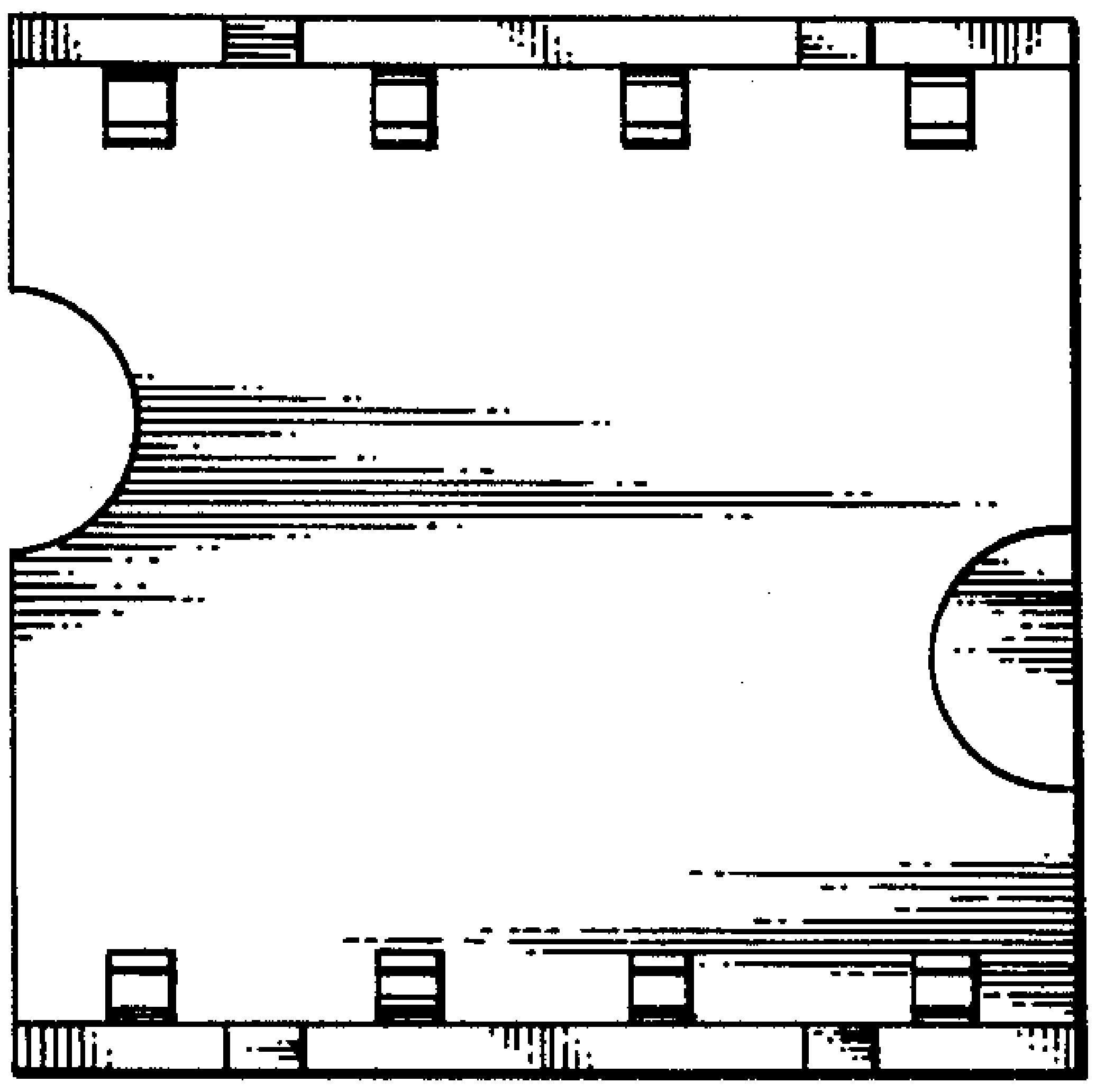


Fig. 7

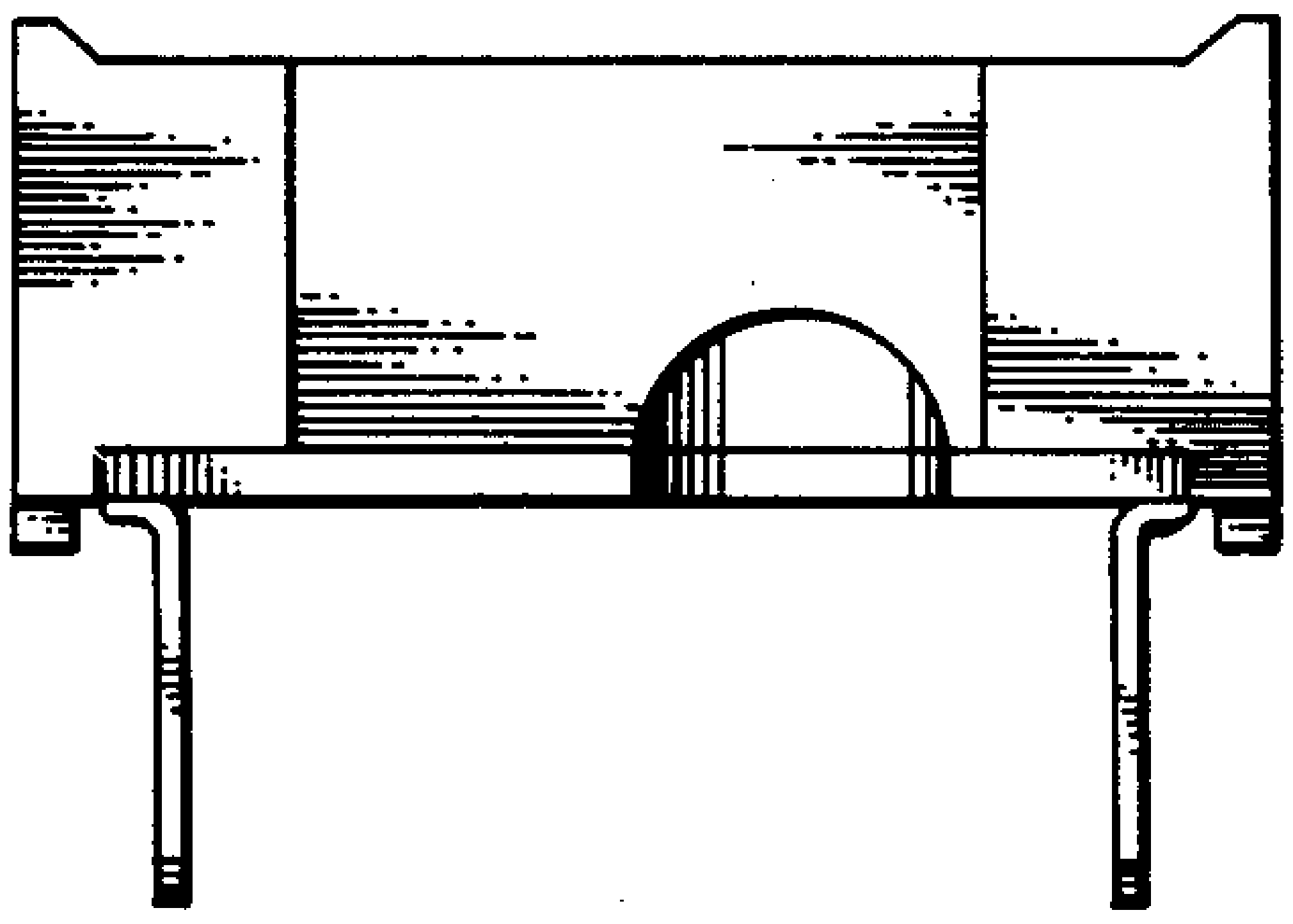


Fig. 8

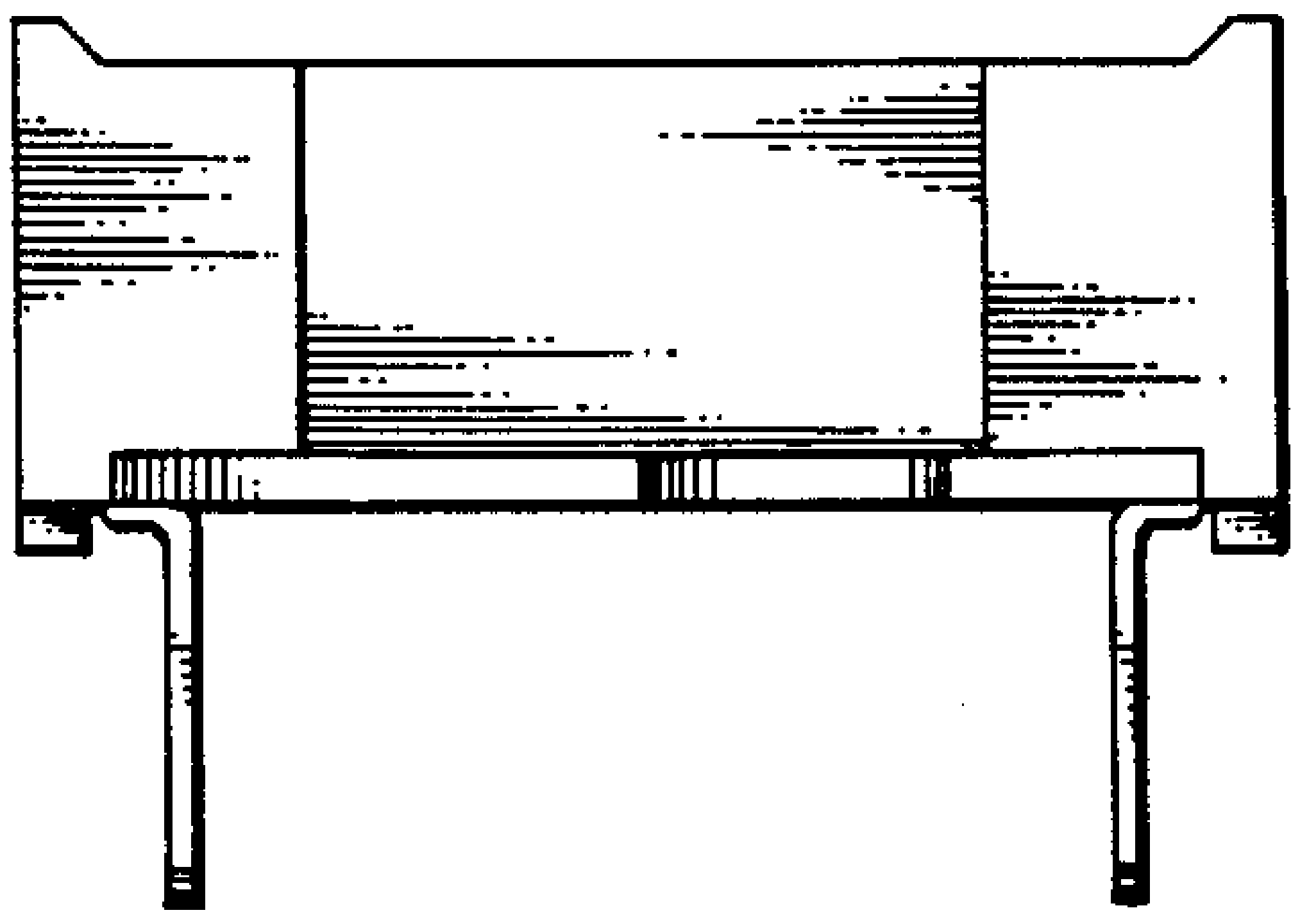


Fig. 9

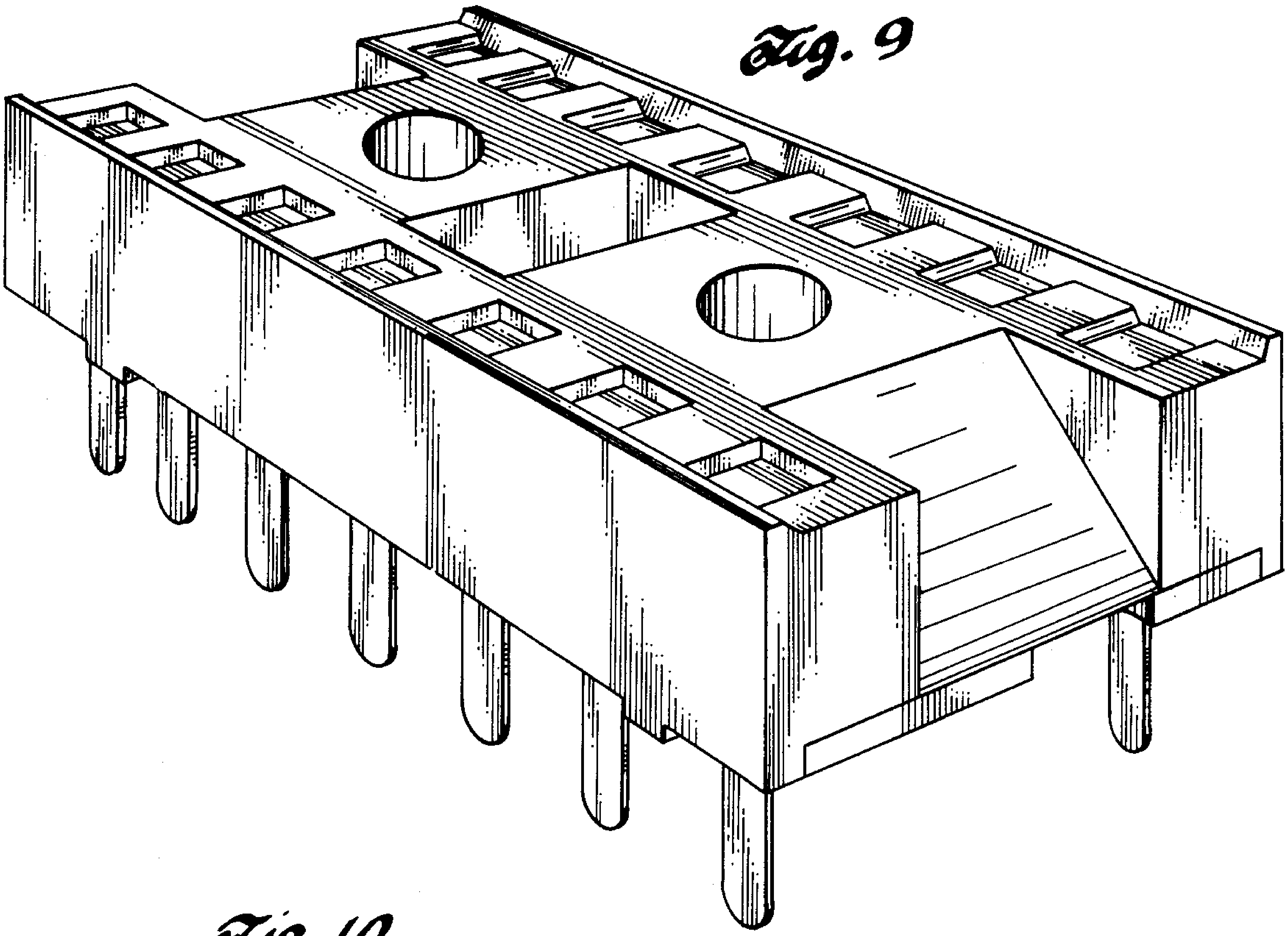


Fig. 10